Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	24258	(chip$1 or (flip adj2 chip)) and pad$1 and solder$1	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:34
L2	12316	1 and (mount$3 near7 surface$1)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:35
L3	11905	2 and connect$3	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:37
L4	6531	3 and mount$3.clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:37
L5	5039	4 and connect$3.clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:37
L6	3296	5 and (pad$1.clm. or solder$1.clm.)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:38
L7	1864	6 and ((second or third) near6 connect$3)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:38
L8	525	7 and (third near8 connect$3)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:39
L9	481	8 and (second near10 (base or surface or substrate or wafer or material))	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:39
L10	403	8 and (second near10 (base or surface or substrate or wafer or material)).clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:40
L11	378	10 and (side$1 or edge$1)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:42
L12	364	11 and (second near10 (surface or base))	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:43
L13	224	11 and ((second near10 (surface or base)) near10 mount$3)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:43
L14	197	13 and (terminal$1.clm. or pad$1.clm.)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:44
L15	150	14 and (chip.clm. or (semiconductor adj device).clm.)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:46
L16	112	15 and (solder$1.clm. or bump$1.clm. or bonding.clm.)	US-PGPUB; USPAT	OR	OFF	2005/04/04 07:47

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L15	2668	257/777	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:52
L16	4292	257/778	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:52
L17	5821	15 or 16	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:52
L18	0	17 and "connect$3."	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:52
L19	5596	17 and connect$3	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:53
L20	4050	19 and (connection.clm. or pad$1. clm. or solder.clm.)	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:53
L21	1551	20 and mount$3.clm.	US-PGPUB; USPAT	OR	OFF·	2005/04/04 14:54
L22	895	21 and (second near7 (surface or base))	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:54
L23	706	22 and (second near7 (surface or base)).clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 14:59
L24	622	23 and ((connect$3 or pad$1 or solder) near7 mount$3)	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:00
L25	399	23 and ((connect$3 or pad$1 or solder) near7 mount$3).clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:00
L26	348	25 and ((device or chip) near5 mount$3)	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:00
L27	333	25 and ((device or chip) near3 mount$3)	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:00
L28	264	27 and ((device or chip) near3 mount$3).clm.	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:01
L29	244	28 and (second near6 (connect$3 or pad$1 or solder$1))	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:01
L30	91	28 and (third near6 (connect$3 or pad$1 or solder$1))	US-PGPUB; USPAT	OR	OFF	2005/04/04 15:01